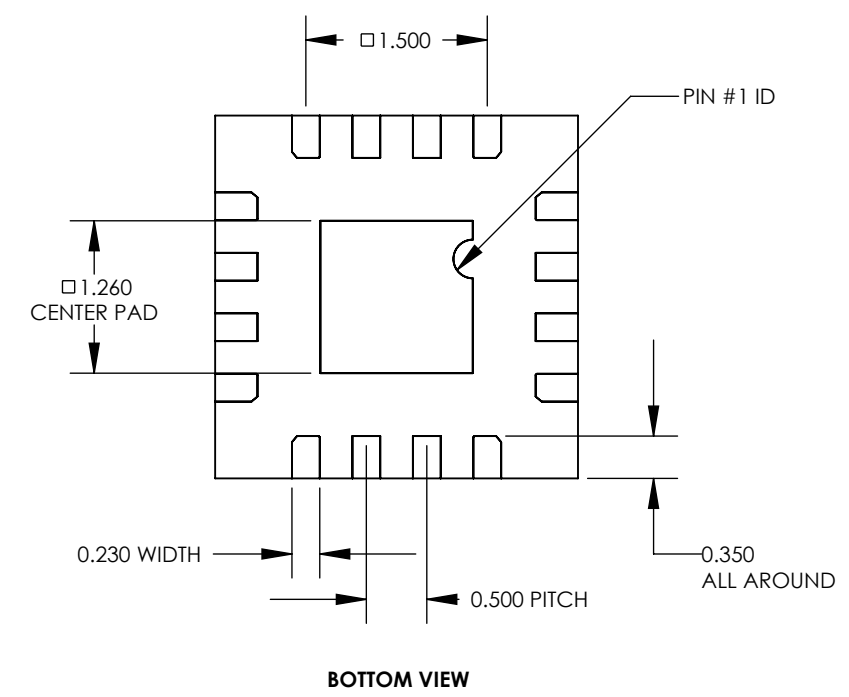
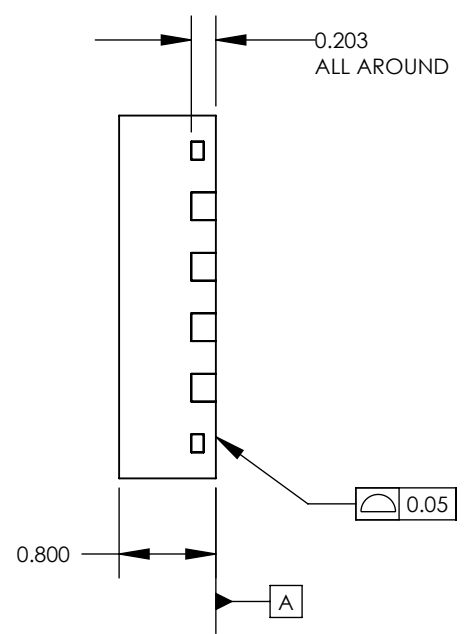
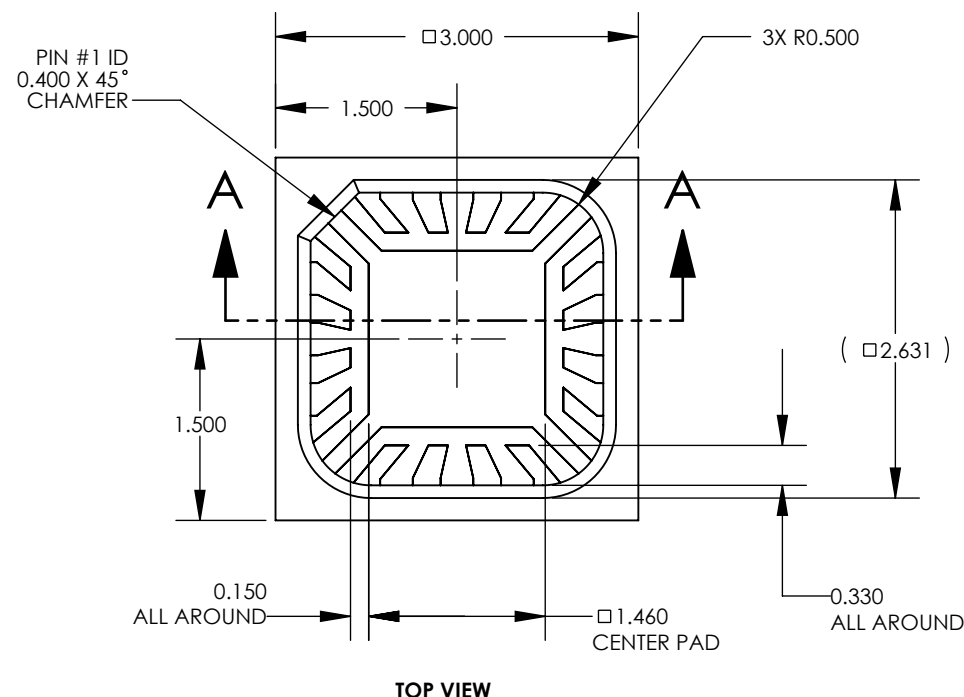
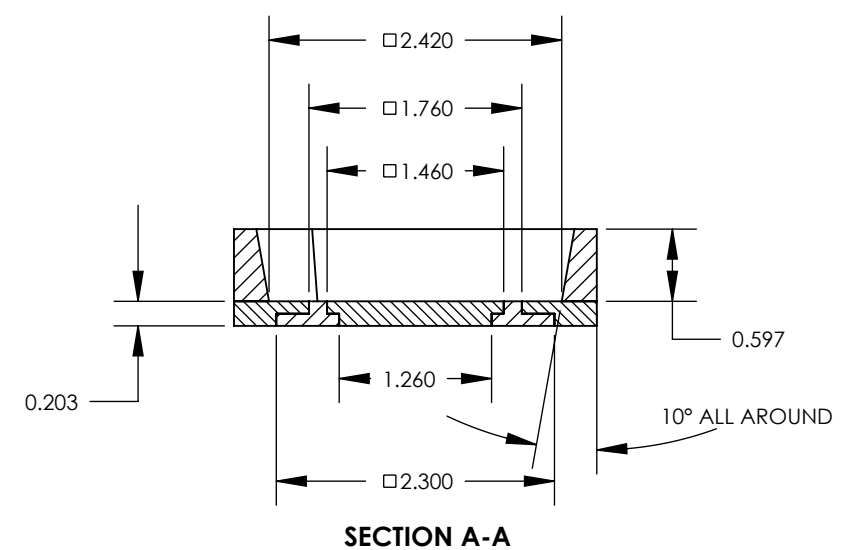


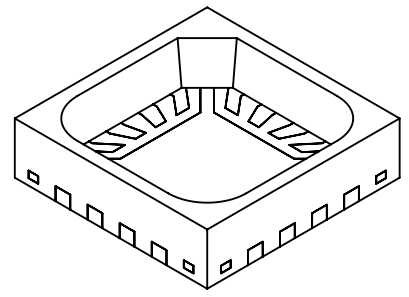
8 7 6 5 4 3 2 1

REVISIONS				
ZONE	REV.	DESCRIPTION	DATE	APPROVED
	A	ORIGINAL RELEASE	7/29/11	SS




**NOTES**

- MATERIALS:**  
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008  
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.
- FINISH:**  
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICROINCHES (2.5um-7.6um) THICK.  
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um-2um) THICK).  
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
- PACKAGE MISMATCH:** BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**
- PACKAGE CONFORMS TO JEDEC MO-220**



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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: ANGULAR: ±0.5 degree .XX: ±0.15 .XXX: ±0.05		NAME	DATE	 <b>QPTECHNOLOGIES</b> <small>A DIVISION OF PROMEX INDUSTRIES   QPTECHNOLOGIES.COM</small>
		DRAWN	D. Abbe	7/29/11	<b>TITLE:</b> QP-QFN16-3MM-0.50MM	
		CHECKED	S. Swen	7/29/11		
		ENG APPR.	S. Swen	7/29/11		
		MATERIAL		COMMENTS:		
		SEE NOTE 1				
		FINISH				
		SEE NOTE 2				
NEXT ASSY	USED ON	DO NOT SCALE DRAWING		SCALE: 16:1	WEIGHT:	SHEET 1 OF 1
				SIZE <b>B</b>	DWG. NO. <b>500372</b>	REV <b>A</b>



8 7 6 5 4 3 2 1